



New Mechanistic Models of Creep-Fatigue Interactions for Gas Turbine Components (DE-FE0011796)

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TEAM AND COLLABORATION

Purdue University

- Thomas Siegmund
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Jay Kruzic (now University New South Wales)

NETL Collaboration

 Jeff Hawk, Albany OR: Material and creep experiments Industry

• i3D MFG, Bend OR: EOS AM Material





MOTIVATION

Cracks: In conventional and AM parts





[1] 2006 Los Angeles Incident, PROBABLE CAUSE: "The HPT stage 1 disk failed from an intergranular fatigue crack"

http://aviation-safety.net/database/record.php?id=20060602-0

[2] Direct Metal Laser Sintering: Karl Wygant et al.; Pump and Turbine 2014





MATERIALS & METHODS

- IN 718 CONV (NETL, J. Hawks)
- IN 718 AM (i3D MFG)
- Microstructure Characterization (Kruzic)
- High Temperature Nanoindentation (Tomar)
- High Temperature Fatigue Crack Growth (Kruzic)
- Computational Mechanics (Siegmund)







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MICROSTR. AND FCG (KRUZIC)

IN 718 CONV









RD





718 samples:

- Rolled, NETL Albany, Jeff Hawk
- Heat treatment steps follow AMS 5662
- Samples: 0.25 in thick, 1.25 in x1.25 in





IN 718 CONV

600 μm



Equiaxed grains •

ND

RD

Only little texture •







IN 718 CONV







180

AVG = 0.42

SDV = 0.15

AVG = 0.53

SDV = 0.12

AVG = 88°

 $SDV = 55^{\circ}$

 $AVG = 85^{\circ}$

 $SDV = 50^{\circ}$

150

1.0

0.8

120

IN 718 AM





Direct metal laser sintered (DMLS) alloy 718 samples:

- _
- _
- _
- _
- EOS M290 printer Pre-alloyed 718 powder supplied by EOS Argon build environment 40 µm layer height EOS proprietary scan pattern (63° rotation between layers) _
- heat treatment AMS 5662 _







IN 718 AM; Print Plane

600 μm





- Finer grains than the CONV
- Rather equiaxed grains in P-P
- Significant texture with 001 aligned in P
 - Transversely isotropic





IN 718 AM: Print Plane











IN 718 AM: Build Plane

600 μm





A1

- Highly elongated grains
- Untextured in P-P and Textured in B
 - Transversely isotropic



IN 718 AM: Build Plane



IN 718 CONV Wrought Fatigue Crack Growth Rates 650°C, Air, R = 0.5, Triangle/Trapezoid da/dN (m) 10⁻⁴ **Differential Image Contrast 10**⁻⁵ Reveals plastic zone da/dN **10**⁻⁶ **ND RD TD 10**⁻⁷ ΔK (MPa *m*^{1/2}) 10 20 50 0.1 Hz 0.1 Hz with 1 min hold at max load 0.014 Hz U V RSITY Ν Ε

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IN 718 CONV



IN 718 CONV Crack growth mechanism (for CREEP AND LOW FREQ.)

- stress assisted grain boundary oxidation (SAGBO)
- Coupled with plastic deformation Crack





At high $\Delta K: O_2$ damage optically visible



IN 718 CONV: Crack Growth Experiments

- IN 718 CONV: At low frequency and 650°C
- Intergranular fracture together with plasticity
- SABO effect
- Time dominates





IN 718 AM: RT





AM Fatigue Crack Growth Rates at 20°C 30 Hz, R = 0.1, Sine



IN 718 AM: 650°C



IN 718 AM: 650°C, R=0.5, 0.1 Hz No growth below Δ K=28 MPa.m^{1/2}











IN 718 AM: EBSD 650°C, R=0.5, 0.1 Hz, ∆K>16 MPa.m^{1/2}

Detail







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IN 718 AM Crack Growth Experiments

- IN 718 AM: At RT
- High da/dN and low threshold
- IN 718: At high frequency and 650°C
- Transgranular fracture with fissures, plasticity
- Cycling dominates
- IN 718: At low frequency and 650°C
- Intergranular fracture along Build-plane GB
- Transgranular fracture across Print-plane grains
- Strong crack deflection





IN 718 CONV vs. IN 718 AM

At RT

- AM exhibits higher da/dN than CONV and
- Lower threshold value

At 650 °C and low rates

CONV fails intergranular, GB are SAGBO effected,

At 650 °C and low rates

- CONV fails intergranular, GB are SAGBO effected,
- FCG is time dominant
- AM crack growth is a mix of transgranular and intergranular
- SAGBO affects built-plane GB
- Strong crack path deflection



NANOINDENTATION (TOMAR)

High Temperature Nanoindentation

An efficient method for the determination of viscoplastic and creep properties of metallic solids

$$H = \frac{P}{A}, A = 3\sqrt{3}(h - \frac{1}{4}P \cdot c)^2 \tan^2 65.3^\circ$$
$$H \approx 3\sigma_{\gamma}(h)$$

$$\dot{\varepsilon} = \frac{h}{h}, \sigma \propto \frac{P}{h^2}$$
$$\dot{\varepsilon} = K\sigma^n, n = \frac{\log(\dot{\varepsilon})}{\log(\sigma)}$$





Berkovich Indenter C-BN



Hardness at Room Temperature



Hardness at 650°C





Indentation Size Effect - Summary

	no dwelling			1000 sec dwelling period				
	CONV	AM	AM	CONV	AM	AM		
		(normal to	(parallel to		(normal to	(parallel to		
		build	build		build	build		
		direction)	direction)		direction)	direction)		
Room Temperature								
h* (nm)	472.64	878.38	4666.06	201.89	404.51	2722.94		
H ₀ (GPa)	5.78	4.84	4.61	5.60	4.80	4.43		
650° C Temperature								
h* (nm)	817.04	596.78	1217.31	2155.62	2758.44	672.07		
H _o (GPa)	4.74	4.17	6.51	3.32	3.07	6.295		





Size Effects in Plasticity of IN 718

- In IN 718 AM, hardness is anisotropic. Hardness is highest when indenting in the build direction.
- In both IN 718 AM and IN 718 CONV a size effect of hardness was found at RT and 650°C.
- The size effect is stronger at 650°C than at RT for two IN 718 CONV and IN 718 AM (↓ to print plane) but less in IN 718 AM (↓ to build plane)





Creep at RT and 650oC







Indentation Creep of IN 718

- Indentation appears as a viable low-cost approach to the determination of creep exponents
- Creep rates decline with low loads and low indention depth. This also indicates a size effect.
- Creep response of IN 716 AM was found to be anisotropic





COMPUTATIONS (SIEGMUND)

Computational Mechanics

Constitutive Models:

- Strain Gradient Viscoplastic Theory, justified by indentation experiments
- Tension-compression asymmetric yield theory, justified by IN 718 literature data

Crack Growth Models:

- Cohesive Zone Model
- Time independent (transgranular)
- Time dependent (SAGBOE)





Unified Viscoplastic Constitutive Models With Strain Gradients

Flow stress

$$\sigma_{\rm flow} = \sigma_0 + M \alpha \mu b \sqrt{\rho}$$

- σ_0 : stress related to lattice friction and solute contents
- *M*: average Taylor factor ($M \approx 3$)
- α : weighting factor of dislocation interactions ($\alpha \approx 1/3$)
- μ : shear modulus
- *b*: Burgers vector





Dislocations: Carriers of Plastic Deformation

Dislocation density: $\rho = \rho_S + \rho_G$

- Statistically stored dislocation:

$$\rho_{S} = \frac{\sqrt{3\overline{\varepsilon}^{vp}}}{b\Lambda}$$



- Geometrically necessary dislocation:

$$\rho_{G} = \overline{r} \, \frac{\overline{\eta}}{b}$$



 $\overline{\eta}$: effective plastic strain gradient \overline{r} : Nye-factor ($\overline{r} = 1.90$)





Total strain rate:
$$\dot{\boldsymbol{\varepsilon}} = \dot{\boldsymbol{\varepsilon}}^e + \dot{\boldsymbol{\varepsilon}}^{\varphi}$$
Elastic strain rate: $\dot{\boldsymbol{\sigma}} = \mathbf{D} \dot{\boldsymbol{\varepsilon}}^e$ Elastic strain rate: $\dot{\boldsymbol{\sigma}} = \mathbf{D} \dot{\boldsymbol{\varepsilon}}^e$ $D_{y|kl} = \mu(\delta_{ik}\delta_{jl} + \delta_{il}\delta_{jk}) + \lambda \delta_{ij}\delta_{kl}$ Viscoplastic strain rate:Lamé's coefficients: λ, μ Kinetic equation: $\frac{\overline{\sigma}}{\sigma_{flow}} = \left(\frac{\dot{\overline{\varepsilon}}^{ep}}{\dot{\varepsilon}_0}\right)^{1/m}$ Kinetic equation: $\frac{\overline{\sigma}}{\sigma_{flow}} = \left(\frac{\dot{\overline{\varepsilon}}^{ep}}{\dot{\varepsilon}_0}\right)^{1/m}$ Taylor equation: $\sigma_{flow} = \sigma_0 + M \alpha \mu b \sqrt{\rho}$ Dislocation density: $\rho = \rho_5 + \rho_G$ Statistically stored dislocation $\rho_G = \overline{r} \cdot \overline{D}^{w}_{b}; \quad \overline{r} = 1.9$ $\rho_S = \rho_S^+ + \rho_S^-$.Initial density: $\rho = \rho_S + \rho_G$ Statistically stored dislocation $\rho_G = \overline{r} \cdot \overline{D}^{w}_{b}; \quad \overline{r} = 1.9$ Effective strain gradient: $\overline{\eta}^w = \sqrt{\frac{1}{4} \eta^w_{bk} \eta^w_{bk}}$ where $\eta_{bk}^w = \varepsilon_{bk,j}^w + \varepsilon_{jk,j}^w - \varepsilon_{bj,k}^w$ Constraint: $\rho_G \leq \rho_G^{max}$ Strain rate sensitivity: $\mu_G \leq \rho_G^{max}$ $k_2 = k_{20} \left(\frac{\dot{\overline{\varepsilon}^{ep}}{\overline{\varepsilon}_0}\right)^{-1/n}$ UMAT-ABAQUS

Oregon State

Example: Viscoplasticity to Creep Response in Presence of a Gradient



- Unify plastic deformation and Creep (indent-hold)
- Size effects increase with time in agreement with results from indentation

 $U_{y} = 0$





Creep-Fatigue Crack Growth

- Fatigue damage and time dependent damage evolve independently and act additively
- Embedded in FEM as a Cohesive Zone Model
 - Cyclic damage law for transgranular crack growth
 - Time damage law SAGBO intergranular crack growth









(a)





E (GPa)	v	σ_0 (MPa)	т	п	k ₁ (mm ⁻¹)	k ₂₀	М	α	b (nm)	$\dot{\mathcal{E}}_0$ (s ⁻¹)	$\rho_0 \ (mm^{-2})$	ρ_G^{\max} (mm^{-2})
165	0.3	779	25	5	8·10 ⁵	28.29	1.73	0.3	0.25	10-3	105	1010

MBL	ICZM	Time Dep. damage
$r_b/l_e = 10,000$	$\delta_0 = 0.4 \times \min l_e (7.36 \times 10^{-6} m)$	p = 6
$L/l_{e} = 110$	$\sigma_{\max,0} = 4\sigma_{y}$	q = 5
$\Delta G/\phi_0 = 0.2$	$\sigma_f / \sigma_{\max,0} = 0.25$	$C = 2000 MPa$ $T_{c} = 600 MPa$
$\phi_0 = 62 \ kJ/m^2$	$\delta_{\Sigma}/\delta_0 = 4$	$T_c = 000$ MI u
f = 5 Hz	$k_{penalty} = 30$	
$\min l_e = 1.84 \times 10^{-5} m$		

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Creep-Fatigue Crack Growth Simulations



Creep-fatigue crack growth emerges as a complex 0.7 interaction of creep & stress relaxation in the bulk 0.6 together with cyclic & time/dependent damage $^{1/3}$, $T_c = 200 MP$ 0.5 Fatigue Damage dominates: high freq. case 0.6 Time Damage dominates: low frequency case 0.7 Time Damage dominates: low frequency case

Creep-Fatigue Crack Growth Simulations







Crack Growth Simulations: Soft→ Hard



Accounting for plastic strain gradients alters how a crack interacts with a weak interface



For L=0 the deflection into the interface is overpredicted



Crack Growth Simulations: Hard → Soft







Crack Growth Simulations: Hard → Soft







Computational Mechanics

Implemented a strain gradient, unified viscoplastic constitutive theory needed for the description of the deformation response of IN718

The unified viscoplastic strain gradient model explains the increase of strain gradient effect with hold times

Creep-fatigue crack growth emerges from the competition of viscoplasticity (augmented by strain gradients), cycledependent and time-dependent damage

What constitutes a weak interface depends on plasticity





CONCLUSION

Creep-fatigue crack growth in IN 718 AM and IN 718 CONV differs substantially

Microstructure differences: grain size and shape, texture

Viscoplastic properties of IN 718 AM are anisotropic, grain size appears to contribute to differences between AM and CONV. In both AM and CONV a size effect in the viscoplastic response has been documented

Time dependent crack growth emerges from the interaction of viscoplasticity in the bulk and the rate dependence of the material separation process

Crack growth response appears as strongly directional in IN 718 AM as a mix of growth along weak intergranular build-direction GBs and across strong transgranular grains.

What constitutes a weak interface depends on understanding of plasticity in the adjacent grains





CONCLUSION

Creep-fatigue crack growth in IN 718 AM and IN 718 CONV differs substantially

Microstructure differences: grain size and shape, texture In IN 718 AM EOS the weak plane is not P-P but P-B

Viscoplastic properties of IN 718 AM are anisotropic, grain size appears to contribute to differences between AM and CONV. In both AM and CONV a size effect in the viscoplastic response has been documented

Time dependent crack growth emerges from the interaction of viscoplasticity in the bulk and the rate dependence of the material separation process

Crack growth response appears as strongly directional in IN 718 AM as a mix of growth along weak intergranular build-direction GBs and across strong transgranular grains.

What constitutes a weak interface depends on understanding of plasticity in the adjacent grains





CONTRIBUTION

Fundamentals

Differences in CONV and AM materials Fracture mechanics of complex microstructures Size effects in viscoplasticity Unified viscoplasticity Crack growth simulation models for AM

Turbines

Advance AM material implementation Advanced stress and deformation analysis Increased systems reliability



